

L Number	Hits	Search Text	DB	Time stamp
1	2998	257/697 438/612	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:10
2	56	(257/697 438/612) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 18:48
3	12	("4021838" "4074342" "4338621" "4561006" "4823234" "4866841" "4893174" "4953060" "5006922" "5016087" "5025347" "5266912").PN.	USPAT	2002/07/14 18:53
4	4	5485039.URPN.	USPAT	2002/07/14 18:54
5	2	3654694.URPN.	USPAT	2002/07/14 18:56
6	7	6001724.URPN.	USPAT	2002/07/14 18:57
7	0	6165888.URPN.	USPAT	2002/07/14 18:59
8	21	("4603802" "4661192" "4907734" "5014111" "5201454" "5249450" "5293073" "5302550" "5421503" "5550407" "5558270" "5633204" "5740956" "5871141" "5874780" "5884830" "5938105" "6001724" "6041995" "6080651" "6098868").PN.	USPAT	2002/07/14 18:59
9	13	5874780.URPN.	USPAT	2002/07/14 19:04
10	1	6204089.URPN.	USPAT	2002/07/14 19:07
11	9	("5376584" "5468655" "5478007" "5795818" "5854514" "5874780" "5894173" "5916407" "6005292").PN.	USPAT	2002/07/14 19:07
12	1	"5874780".PN.	USPAT	2002/07/14 19:08
13	7	("5037780" "5070604" "5348214" "5410807" "5478007" "5518964" "5615824").PN.	USPAT	2002/07/14 19:09
14	1121	257/697	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:11
15	790	257/697 and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:11
16	422	(257/697 and (method process)) and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:12
17	297	((257/697 and (method process)) and solder and pad) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:13
18	283	((257/697 and (method process)) and solder and pad) and pin) not ((257/697 438/612) and jig)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:45
19	19	("3676832" "4322119" "4420205" "4498725" "4773873" "4950980" "5384692" "5637008" "5669774" "5691041" "5707247" "5714803" "5749999" "5766021" "5783461" "5805419" "5808474" "5812378" "6069023").PN.	USPAT	2002/07/14 19:15
20	1	6229207.URPN.	USPAT	2002/07/14 19:21

21	1	6229207.URPN.	USPAT	2002/07/14 19:21
22	20	("4170472" "4290079" "4824009" "5102829" "5237130" "5288944" "5303862" "5468995" "5541450" "5625166" "5625944" "5640047" "5641990" "5831336" "5834839" "5847929" "5868304" "5907187" "5938862" "5959348").PN.	USPAT	2002/07/14 19:21
23	15	5288944.URPN.	USPAT	2002/07/14 19:23
24	3	("4338621" "4513355" "5041396").PN.	USPAT	2002/07/14 19:24
25	3	5943217.URPN.	USPAT	2002/07/14 19:31
26	8	("4087906" "4435741" "4752027" "4893174" "4899207" "4982265" "5167361" "5425647").PN.	USPAT	2002/07/14 19:31
27	15	5789810.URPN.	USPAT	2002/07/14 19:37
28	8	("3962899" "4113522" "4145903" "4177665" "5023398" "5233225" "5397917" "5455457").PN.	USPAT	2002/07/14 19:39
29	38	(257/697 438/612) and (pin with (attachment attaching attached) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:46
30	11	(257/697 438/612) and (pin with (attachment attaching attached) with pad with solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:55
31	1	6214642.URPN.	USPAT	2002/07/14 19:52
32	9	("5436503" "5521435" "5598036" "5641996" "5666008" "5705858" "5708304" "5834848" "5912507").PN.	USPAT	2002/07/14 19:53
33	27	((257/697 438/612) and (pin with (attachment attaching attached) with pad)) not ((257/697 438/612) and (pin with (attachment attaching attached) with pad with solder))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:55
34	242	(solder adj (resist mask)) near3 (polymer polymeric plastic polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:33
35	9	(257/697 438/612) and ((solder adj (resist mask)) near3 (polymer polymeric plastic polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:59
42	429	flux near2 (polymer polymeric plastic polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:36
43	1	((solder adj (resist mask)) near3 (polymer polymeric plastic polyimide)) with flux	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:34
44	3	(257/697 438/612) and (flux near2 (polymer polymeric plastic polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:35
45	2	(flux near2 (polymer polymeric plastic polyimide)) and (pin adj grid adj array)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:36
46	771	flux near3 (polymer polymeric plastic polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:37

47	5	(257/697 438/612) and (flux near3 (polymer polymeric plastic polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:42
48	0	cyclohexyldiepoxyde near3 (polymer polymeric plastic polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:43
49	6	cyclohexyldiepoxyde	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 20:43
-	52	((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18
-	2	("5249100" "6300678").PN.	USPAT	2002/07/12 15:58
-	6	5249100.URPN.	USPAT	2002/07/12 15:59
-	4	("3645785" "3855693" "4702941" "4918811").PN.	USPAT	2002/07/12 15:59
-	1	6300678.URPN.	USPAT	2002/07/12 16:00
-	9	("4949455" "5041901" "5061552" "5145104" "5334804" "5410807" "5533665" "5642261" "5912510").PN.	USPAT	2002/07/12 16:00
-	9	("4949455" "5041901" "5061552" "5145104" "5334804" "5410807" "5533665" "5642261" "5912510").PN.	USPAT	2002/07/12 16:02
-	0	6413849.URPN.	USPAT	2002/07/12 16:02
-	8	("4634041" "4970570" "5442239" "5448016" "5640052" "5718367" "6054652" "6077725").PN.	USPAT	2002/07/12 16:03
-	17	5640052.URPN.	USPAT	2002/07/12 16:04
-	2	6054652.URPN.	USPAT	2002/07/12 16:08
-	8	("4634041" "4970570" "5442239" "5448016" "5640052" "5718367" "6054652" "6077725").PN.	USPAT	2002/07/12 16:09
-	0	6413849.URPN.	USPAT	2002/07/12 16:09
-	8	("4634041" "4970570" "5442239" "5448016" "5640052" "5718367" "6054652" "6077725").PN.	USPAT	2002/07/12 16:09
-	4	("5421083" "5432675" "5543586" "5834705").PN.	USPAT	2002/07/12 16:09
-	5986	((pin adj grid adj array) pga) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	170	((pin adj grid adj array) pga) and (method process)) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	55	((pin adj grid adj array) pga) and (method process)) and jig) and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	51	((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:15

-	12	(((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))) and substrate and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:16
-	107	((providing near3 substrate) and ((attaching soldering) near3 pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18
-	2	((providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:31
-	18	((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polyimide plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:33

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6	7	6001724.URPN.	USPAT	2002/07/14 18:57
7	0	6165888.URPN.	USPAT	2002/07/14 18:59
8	21	("4603802" "4661192" "4907734" "5014111" "5201454" "5249450" "5293073" "5302550" "5421503" "5550407" "5558270" "5633204" "5740956" "5871141" "5874780" "5884830" "5938105" "6001724" "6041995" "6080651" "6098868").PN.	USPAT	2002/07/14 18:59
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13	7	("5037780" "5070604" "5348214" "5410807" "5478007" "5518964" "5615824").PN.	USPAT	2002/07/14 19:09
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16	422	(257/697 and (method process)) and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:12
17	297	((257/697 and (method process)) and solder and pad) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:13
18	283	((257/697 and (method process)) and solder and pad) and pin) not ((257/697 438/612) and jig)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:45
19	19	("3676832" "4322119" "4420205" "4498725" "4773873" "4950980" "5384692" "5637008" "5669774" "5691041" "5707247" "5714803" "5749999" "5766021" "5783461" "5805419" "5808474" "5812378" "6069023").PN.	USPAT	2002/07/14 19:15
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24	3	("4338621" "4513355" "5041396").PN.	USPAT	2002/07/14 19:24
25	3	5943217.URPN.	USPAT	2002/07/14 19:31
26	8	("4087906" "4435741" "4752027" "4893174" "4899207" "4982265" "5167361" "5425647").PN.	USPAT	2002/07/14 19:31
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33	27	((257/697 438/612) and (pin with attachment attaching attached) with pad)) not ((257/697 438/612) and (pin with attachment attaching attached) with pad with solder))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:55
34	242	(solder adj (resist mask)) near3 (polymer polymeric plastic polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:59
35	9	(257/697 438/612) and ((solder adj (resist mask)) near3 (polymer polymeric plastic polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:59
-	52	(providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18
-	2	("5249100" "6300678").PN.	USPAT	2002/07/12 15:58
-	6	5249100.URPN.	USPAT	2002/07/12 15:59
-	4	("3645785" "3855693" "4702941" "4918811").PN.	USPAT	2002/07/12 15:59
-	1	6300678.URPN.	USPAT	2002/07/12 16:00
-	9	("4949455" "5041901" "5061552" "5145104" "5334804" "5410807" "5533665" "5642261" "5912510").PN.	USPAT	2002/07/12 16:00
-	9	("4949455" "5041901" "5061552" "5145104" "5334804" "5410807" "5533665" "5642261" "5912510").PN.	USPAT	2002/07/12 16:02
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-	2	6054652.URPN.	USPAT	2002/07/12 16:08
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-	0	6413849.URPN.	USPAT	2002/07/12 16:09
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-	4	("5421083" "5432675" "5543586" "5834705").PN.	USPAT	2002/07/12 16:09
-	5986	((pin adj grid adj array) pga) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	170	((pin adj grid adj array) pga) and (method process)) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	55	((pin adj grid adj array) pga) and (method process)) and jig) and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
-	51	((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:15
-	12	((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))) and substrate and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:16
-	107	(providing near3 substrate) and ((attaching soldering) near3 pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18
-	2	(providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:31
-	18	((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polyimide plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:33